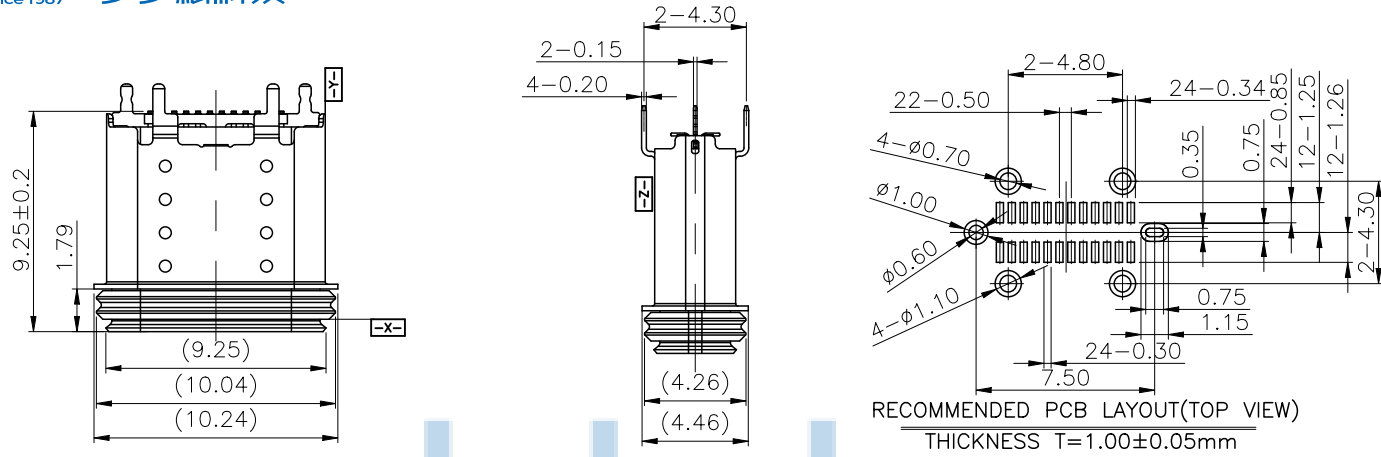


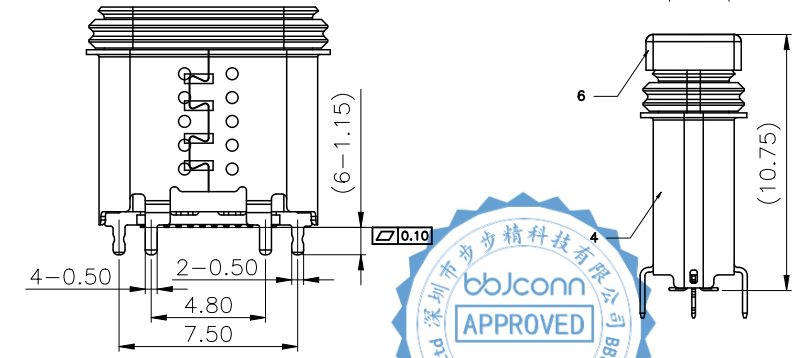
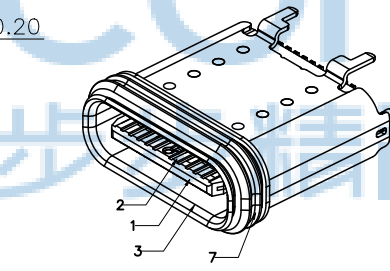
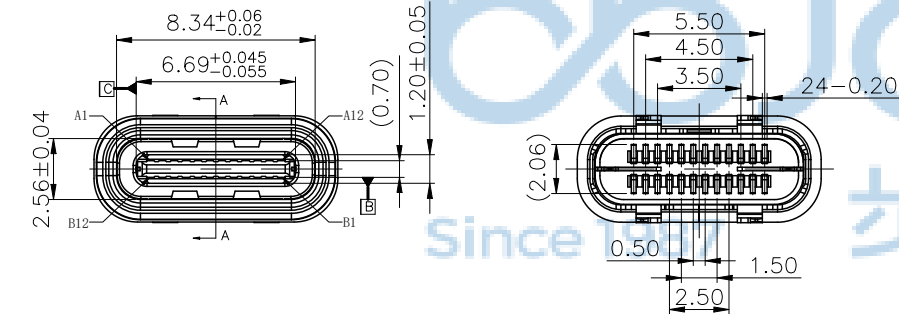
REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF

MAIN SPECIFICATION:

- VOLTAGE/CURRENT RATING: 5V/5.0 A
电流: 5V/5.0 A
- DIELECTRIC WITHSTAND VOLTAGE: 100VAC
耐电压: 100VAC MAX
- TEMPERATURE RANGE: -30 °C ~ 85 °C
使用温度: -30 °C ~ 85 °C
- INITIAL CONTACT RESISTANCE: 40 MILLIONHM MAX
初始接触电阻: 40 MILLIONHM MAX
AFTER TEST: 50 MILLIONHM MAX ALL CONTACTS.
寿命后接触电阻: 50 MILLIONHM MAX
- INSULATION RESISTANCE: 100 MEGOHMS MIN.
绝缘阻抗: 100 MEGOHMS MIN.
- INITIAL INSERTION FORCE 5-20N, EXTRACTION FORCE: 8-20N
初始插入力: 5-20N; 初始拔出: 8-20N。
- AFTER DURABILITY (10000CYCLES) INSERTION FORCE 5-20N
EXTACTION FORCE: 6-20N
寿命后 (10000次) 插入力: 5-20N;
拔出: 6-20N。
- WATERPROOF GRADE: IPX7
防水等级: IPX7.



RECOMMENDED PCB LAYOUT (TOP VIEW)
THICKNESS T=1.00±0.05mm



7	SEALING	1	SILICON DIOXIDE
6	CAP	1	HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
5	MID PLATE	1	STAINLESS STEEL, PLATED NICKEL 50u"MIN
4	OUTER SHELL	1	STAINLESS STEEL, PLATED NICKEL 50u"MIN
3	MAIN SHELL	1	STAINLESS STEEL, PLATING NICKEL 50u"MIN
2	CONTACT	24	COPPER ALLOY, NI PLATING OVER ALL, AU1u" PLATING ON CONTACT AREA, AU1u" PLATING ON SOLDER AREA
1	OVER MOLDING	1	HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
Item	PART NAME.	QUANTITY	NOTE

USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
SIGNAL NAME	GND	SSTXp1	SSTXn1	Vbus	CC1	Dp1	Dn1	SBU1	Vbus	SSRXn2	SSRXp2	GND
PIN NUMBER	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
SIGNAL NAME	GND	SSRXp1	SSRXn1	Vbus	SBU2	Dn2	Dp2	CC2	Vbus	SSTXn2	SSTXp2	GND

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PDWG NO: 0482-1

DR SGF

APPD JM_Zheng

CHKD LYX

FINISH: SEE NOTES

SCALE: N/A

REV: A0

UNIT: mm

PAGE: 1/3

NAME: TYPE-C 24P 防水母座 直立式 六脚插 H=9.25 端子SMT IPX7 加盖编带

PJ NO: 126-224-240006-H8G

SIZE: A4

DRW NO:

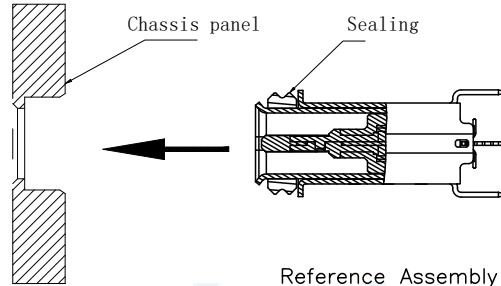
MAT'L: SEE NOTES

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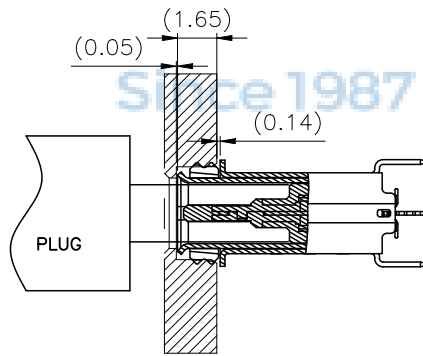
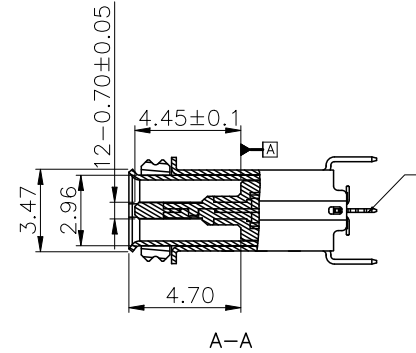


REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF

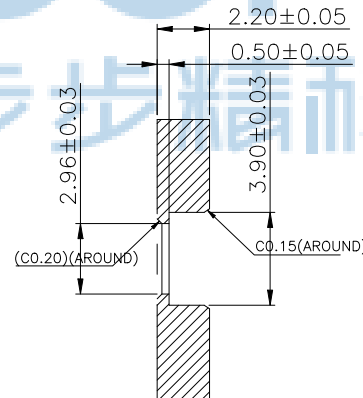
Recommended sealing method



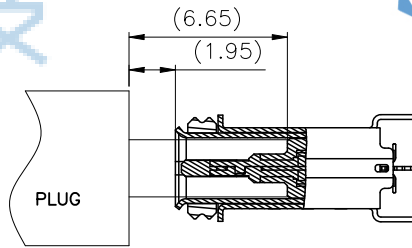
Reference Assembly direction



Reference assembly schematic



Reference dimensions



AFTER MATING

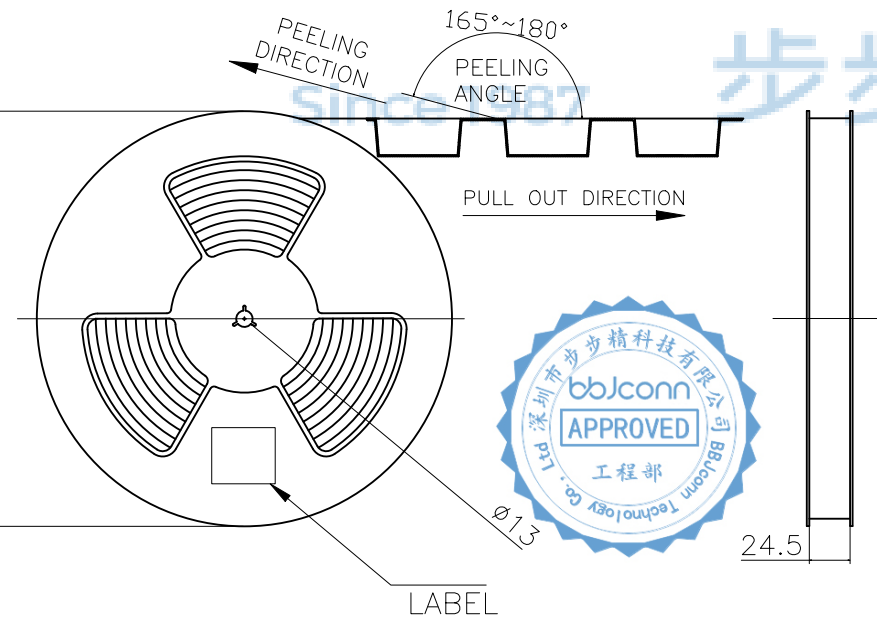
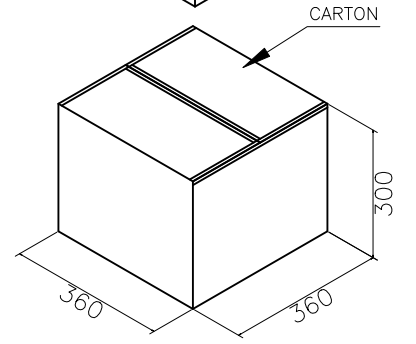
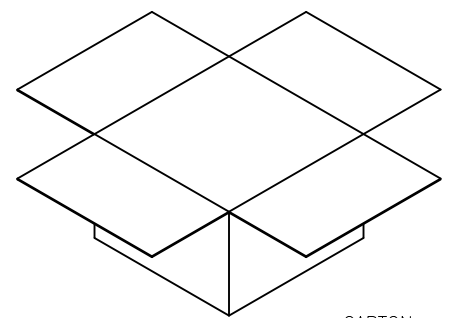
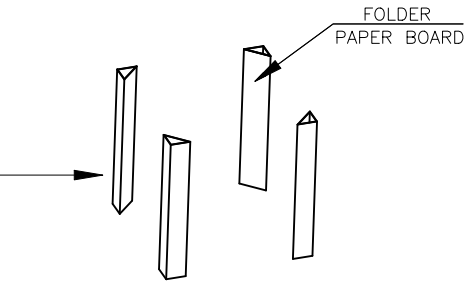
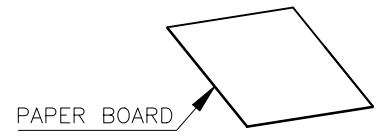
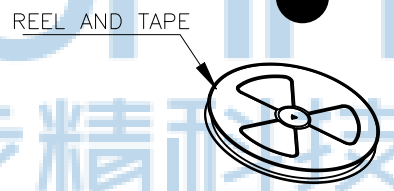
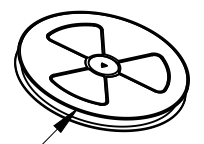
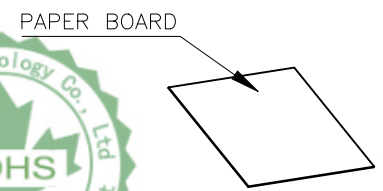
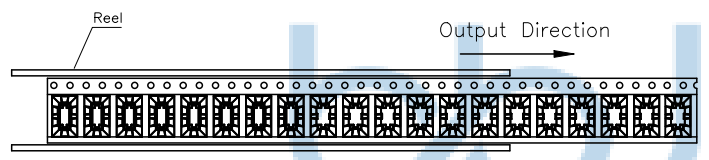
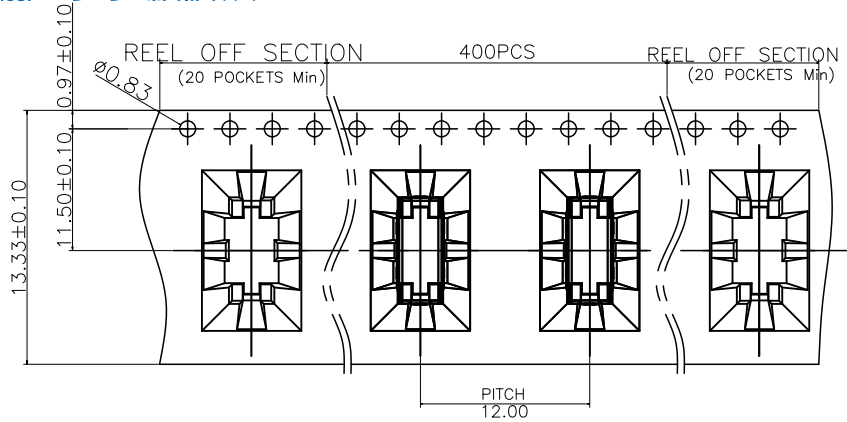


Note:
It is recommended that the shrinkage between the chassis panel and the sealing ring be 0.20-0.40

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深圳市步步精科技有限公司		
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3" X'': ±2" X'X': ±1"	NAME: TYPE-C 24P 防水母座 直立式 六脚插 H=9.25 端子SMT IPX7 加盖编带
APPD	JM_Zheng	PJ NO: 126-224-240006-H8G
CHKD	LYX	SIZE:A4 DRW NO:
DR	SGF	FINISH:SEE NOTES MAT'L:SEE NOTES SCALE:N/A REV:A0 UNIT:mm PAGE:2/3

REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF



Production parameters	
PCS/Roll	400
Roll/Box	10
PCS/Box	4000

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PDWG NO: 0482-1

深圳市步步精科技有限公司		NAME: TYPE-C 24P 防水母座 直立式 六脚插 H=9.25 端子SMT IPX7 加盖编带			
		PJ NO: 126-224-240006-H8G SIZE:A4 DRW NO:	FINISH:SEE NOTES SCALE:N/A	MAT'L:SEE NOTES REV:A0 UNIT:mm	PAGE:3/3
APPD	JM_Zheng	CHKD	LYX	DR	SGF